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# ZXTDCM832

## MPPS™ Miniature Package Power Solutions DUAL 50V NPN SILICON LOW SATURATION SWITCHING TRANSISTOR

### SUMMARY

$V_{CEO}=50V$ ;  $R_{SAT} = 68m\Omega$ ;  $I_C= 4A$

### DESCRIPTION

Packaged in the innovative 3mm x 2mm MLP (Micro Leaded Package) outline, these new 4<sup>th</sup> generation low saturation dual transistors offer extremely low on state losses making them ideal for use in DC-DC circuits and various driving and power management functions.

Additionally users gain several other **key benefits**:

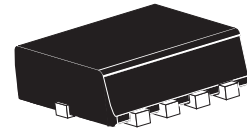
**Performance capability equivalent to much larger packages**

**Improved circuit efficiency & power levels**

**PCB area and device placement savings**

**Lower package height (nom 0.9mm)**

**Reduced component count**



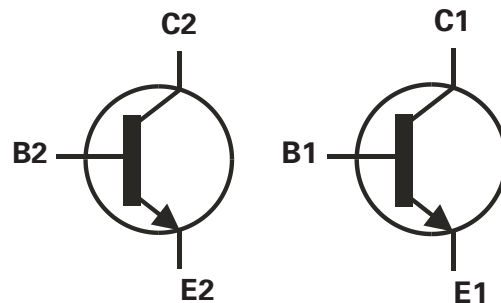
3mm x 2mm (Dual die) MLP

### FEATURES

- Low Equivalent On Resistance
- Extremely Low Saturation Voltage (100mV @1A)
- $h_{FE}$  characterised up to 6A
- $I_C=4A$  Continuous Collector Current
- 3mm x 2mm MLP

### APPLICATIONS

- DC - DC Converters
- Charging circuits
- CCFL Backlighting
- Power switches
- Motor control



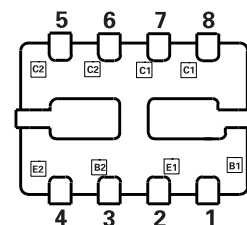
### ORDERING INFORMATION

DEVICE	REEL	TAPE WIDTH	QUANTITY PER REEL
ZXTDCM832TA	7''	8mm	3000
ZXTDCM832TC	13''	8mm	10000

### DEVICE MARKING

DCC

### PINOUT



3mm x 2mm MLP  
underside view

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## ABSOLUTE MAXIMUM RATINGS.

PARAMETER	SYMBOL	LIMIT	UNIT
Collector-Base Voltage	$V_{CBO}$	100	V
Collector-Emitter Voltage	$V_{CEO}$	50	V
Emitter-Base Voltage	$V_{EBO}$	7.5	V
Peak Pulse Current	$I_{CM}$	6	A
Continuous Collector Current (a)(f)	$I_C$	4	A
Base Current	$I_B$	1000	mA
Power Dissipation at TA=25°C (a)(f) Linear Derating Factor	$P_D$	1.5 12	W mW/°C
Power Dissipation at TA=25°C (b)(f) Linear Derating Factor	$P_D$	2.45 19.6	W mW/°C
Power Dissipation at TA=25°C (c)(f) Linear Derating Factor	$P_D$	1 8	W mW/°C
Power Dissipation at TA=25°C (d)(f) Linear Derating Factor	$P_D$	1.13 9	W mW/°C
Power Dissipation at TA=25°C (d)(g) Linear Derating Factor	$P_D$	1.7 13.6	W mW/°C
Power Dissipation at TA=25°C (e)(g) Linear Derating Factor	$P_D$	3 24	W mW/°C
Operating and Storage Temperature Range	$T_j:T_{stg}$	-55 to +150	°C

## THERMAL RESISTANCE

PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a)(f)	$R_{\theta JA}$	83.3	°C/W
Junction to Ambient (b)(f)	$R_{\theta JA}$	51	°C/W
Junction to Ambient (c)(f)	$R_{\theta JA}$	125	°C/W
Junction to Ambient (d)(f)	$R_{\theta JA}$	111	°C/W
Junction to Ambient (d)(g)	$R_{\theta JA}$	73.5	°C/W
Junction to Ambient (e)(g)	$R_{\theta JA}$	41.7	°C/W

### Notes

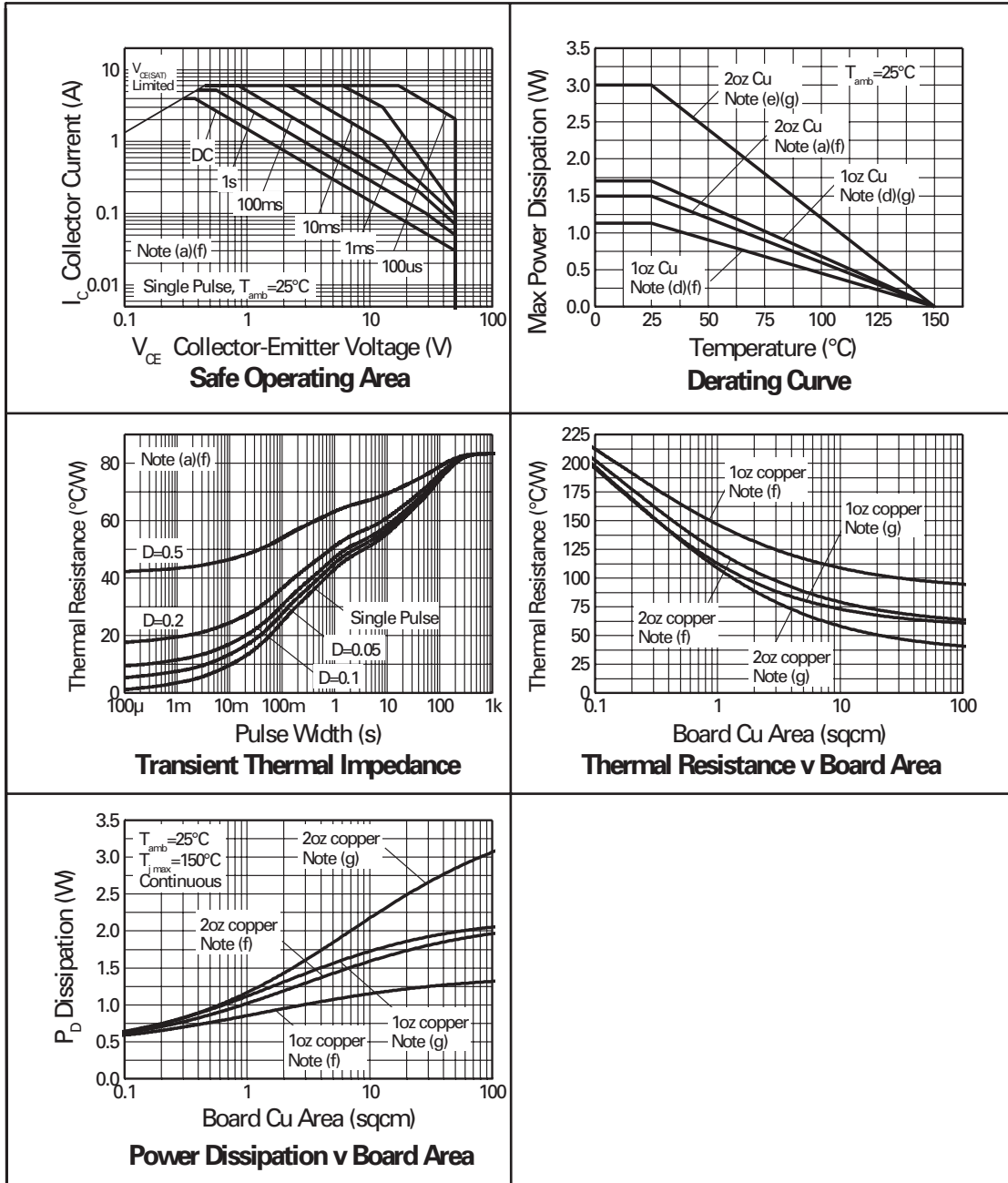
- (a) For a dual device surface mounted on 8 sq cm single sided 2oz copper on FR4 PCB, in still air conditions **with all exposed pads attached**. The copper area is split down the centre line into two separate areas with one half connected to each half of the dual device.
- (b) Measured at t<5 secs for a dual device surface mounted on 8 sq cm single sided 2oz copper on FR4 PCB, in still air conditions **with all exposed pads attached**. The copper area is split down the centre line into two separate areas with one half connected to each half of the dual device.
- (c) For a dual device surface mounted on 8 sq cm single sided 2oz copper on FR4 PCB, in still air conditions **with minimal lead connections only**.
- (d) For a dual device surface mounted on 10 sq cm single sided 1oz copper on FR4 PCB, in still air conditions **with all exposed pads attached attached**. The copper area is split down the centre line into two separate areas with one half connected to each half of the dual device.
- (e) For a dual device surface mounted on 85 sq cm single sided 2oz copper on FR4 PCB, in still air conditions **with all exposed pads attached attached**. The copper area is split down the centre line into two separate areas with one half connected to each half of the dual device.
- (f) For a dual device with one active die.
- (g) For dual device with 2 active die running at equal power.
- (h) Repetitive rating - pulse width limited by max junction temperature. Refer to Transient Thermal Impedance graph.
- (i) The minimum copper dimensions required for mounting are no smaller than the exposed metal pads on the base of the device as shown in the package dimensions data. The thermal resistance for a dual device mounted on 1.5mm thick FR4 board using minimum copper 1 oz weight, 1mm wide tracks and one half of the device active is  $R_{th} = 250^{\circ}C/W$  giving a power rating of  $P_{tot} = 500mW$ .



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## TYPICAL CHARACTERISTICS



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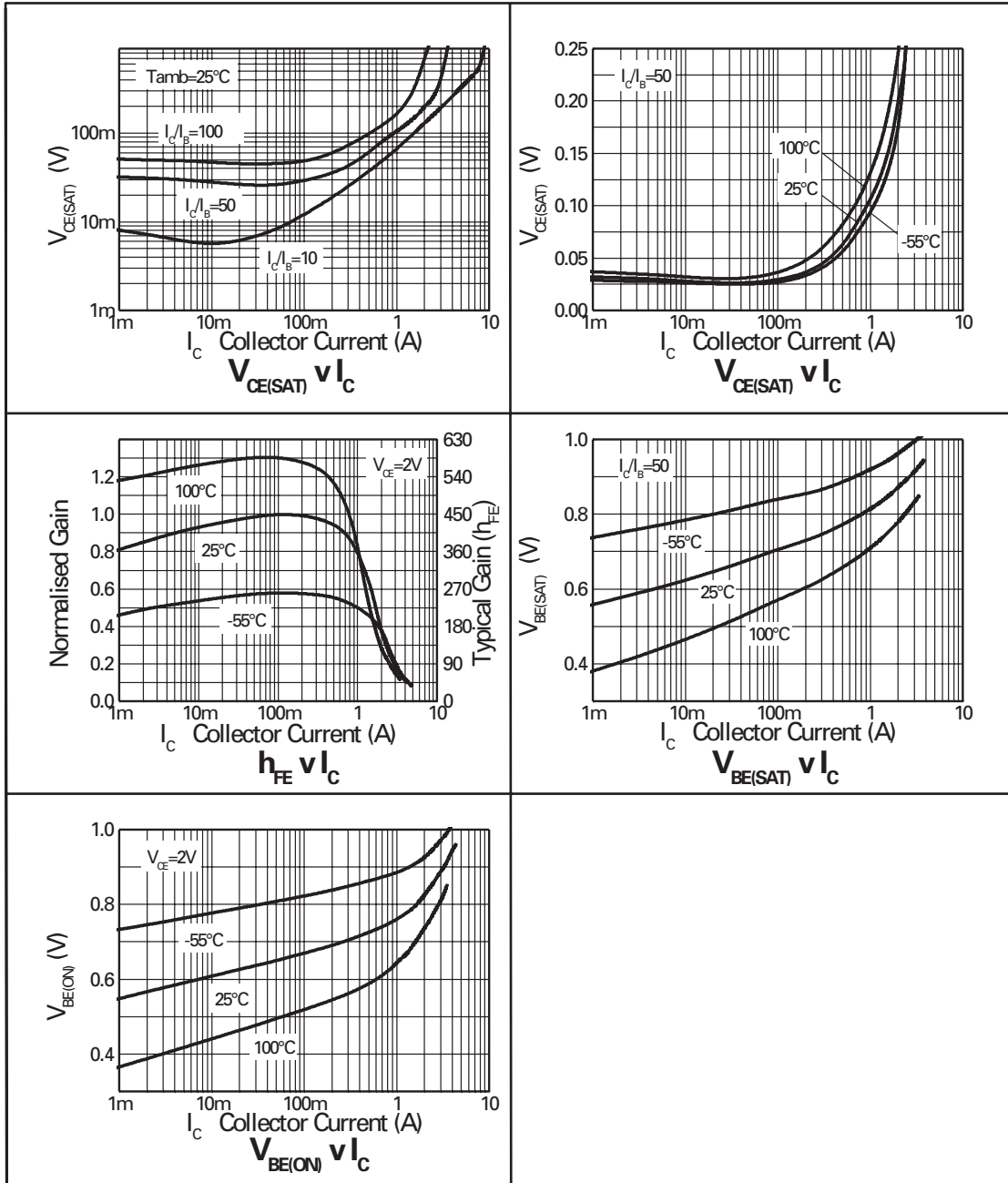
## ELECTRICAL CHARACTERISTICS (at $T_{amb} = 25^{\circ}\text{C}$ unless otherwise stated).

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS.
Collector-Base Breakdown Voltage	$V_{(BR)CBO}$	100	190		V	$I_C=100\mu\text{A}$
Collector-Emitter Breakdown Voltage	$V_{(BR)CEO}$	50	65		V	$I_C=10\text{mA}^*$
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	7.5	8.2		V	$I_E=100\mu\text{A}$
Collector Cut-Off Current	$I_{CBO}$			25	nA	$V_{CB}=80\text{V}$
Emitter Cut-Off Current	$I_{EBO}$			25	nA	$V_{EB}=6\text{V}$
Collector Emitter Cut-Off Current	$I_{CES}$			25	nA	$V_{CES}=40\text{V}$
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$		10	20	mV	$I_C=0.1\text{A}, I_B=10\text{mA}^*$
			70	100	mV	$I_C=1\text{A}, I_B=50\text{mA}^*$
			145	200	mV	$I_C=1\text{A}, I_B=10\text{mA}^*$
			115	220	mV	$I_C=2\text{A}, I_B=50\text{mA}^*$
			225	300	mV	$I_C=3\text{A}, I_B=100\text{mA}^*$
			270	320	mV	$I_C=4\text{A}, I_B=200\text{mA}^*$
Base-Emitter Saturation Voltage	$V_{BE(sat)}$		1.00	1.05	V	$I_C=4\text{A}, I_B=200\text{mA}^*$
Base-Emitter Turn-On Voltage	$V_{BE(on)}$		0.94	1.00	V	$I_C=4\text{A}, V_{CE}=2\text{V}^*$
Static Forward Current Transfer Ratio	$h_{FE}$	200	400			$I_C=10\text{mA}, V_{CE}=2\text{V}^*$
		300	450			$I_C=0.2\text{A}, V_{CE}=2\text{V}^*$
		200	400			$I_C=1\text{A}, V_{CE}=2\text{V}^*$
		100	225			$I_C=2\text{A}, V_{CE}=2\text{V}^*$
			40			$I_C=6\text{A}, V_{CE}=2\text{V}^*$
Transition Frequency	$f_T$	100	165		MHz	$I_C=50\text{mA}, V_{CE}=10\text{V}$ $f=100\text{MHz}$
Output Capacitance	$C_{obo}$		12	20	pF	$V_{CB}=10\text{V}, f=1\text{MHz}$
Turn-On Time	$t_{(on)}$		170		ns	$V_{CC}=10\text{V}, I_C=1\text{A}$
Turn-Off Time	$t_{(off)}$		750		ns	$I_{B1}=I_{B2}=10\text{mA}$

\*Measured under pulsed conditions. Pulse width=300 $\mu\text{s}$ . Duty cycle  $\leq$  2%

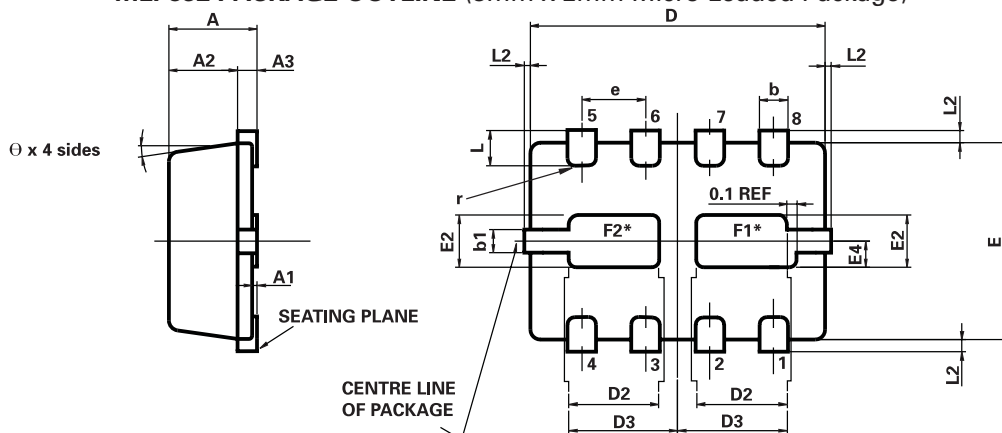
# ZXTDCM832

## TYPICAL CHARACTERISTICS



# ZXTDCM832

## MLP832 PACKAGE OUTLINE (3mm x 2mm Micro Leaded Package)



\*Exposed Flags. Solder connection to improve thermal dissipation is optional.  
 F1 at collector 1 potential  
 F2 at collector 2 potential

CONTROLLING DIMENSIONS IN MILLIMETRES  
 APPROX. CONVERTED DIMENSIONS IN INCHES

### MLP832 PACKAGE DIMENSIONS

DIM	MILLIMETRES		INCHES		DIM	MILLIMETRES		INCHES	
	MIN.	MAX.	MIN.	MAX.		MIN.	MAX.	MIN.	MAX.
A	0.80	1.00	0.031	0.039	e	0.65 REF		0.0256 BSC	
A1	0.00	0.05	0.00	0.002	E	2.00 BSC		0.0787 BSC	
A2	0.65	0.75	0.0255	0.0295	E2	0.43	0.63	0.017	0.0249
A3	0.15	0.25	0.006	0.0098	E4	0.16	0.36	0.006	0.014
b	0.24	0.34	0.009	0.013	L	0.20	0.45	0.0078	0.0157
b1	0.17	0.30	0.0066	0.0118	L2	_____	0.125	0.00	0.005
D	3.00 BSC		0.118 BSC		r	0.075 BSC		0.0029 BSC	
D2	0.82	1.02	0.032	0.040	Ø	0°	12°	0°	12°
D3	1.01	1.21	0.0397	0.0476					

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